

L Number	Hits	Search Text	DB	Time stamp
7	16	(anneal\$3 same copper adj plat\$3 or electroplat\$3 same electropolish\$3 or (electrolytic adj polish\$3)) and conveyor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 11:37
1	612	anneal\$3 same copper adj plat\$3 or electroplat\$3 same electropolish\$3 or (electrolytic adj polish\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 12:01
13	91	(anneal\$3 same copper adj plat\$3 or electroplat\$3 same electropolish\$3 or (electrolytic adj polish\$3)) and 204/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 12:10
19	51	anneal\$3 SAME copper adj electroplat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 12:16
25	1	anneal\$3 SAME copper adj electroplat\$3 AND electropolish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 12:19
31	171966	anneal\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 12:19
37	31602	chemical near5 polish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 12:20
43	6470	anneal\$3 AND (chemical near5 polish\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 12:21
49	4081	electroplat\$3 NEAR copper	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 12:22
55	219	(anneal\$3 AND (chemical near5 polish\$3)) AND (electroplat\$3 NEAR copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 12:25
61	3	((anneal\$3 AND (chemical near5 polish\$3)) AND (electroplat\$3 NEAR copper)) AND conveyor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 12:25
67	0	((anneal\$3 AND (chemical near5 polish\$3)) AND (electroplat\$3 NEAR copper)) AND conveyor AND chemical adj polish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 12:25
73	4	(anneal\$3 AND (chemical near5 polish\$3)) AND (electroplat\$3 NEAR copper) AND chemical adj polish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 12:26
-	275	205/223.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/15 11:31
-	15	205/223.ccls. and interconnect	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/13 18:16
-	14	205/223.ccls. and interconnect and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/13 18:16
-	222	anneal\$3 adj section	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:46

-	0	anneal\$3 adj section SAME electropolish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:41
-	0	anneal\$3 adj section SAME chemical adj polish	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:41
-	1	anneal\$3 adj section SAME chemical adj polish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:41
-	165	anneal\$3 adj area	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:45
-	6	(anneal\$3 adj area) AND (anneal\$3 adj section)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:43
-	1	(anneal\$3 adj section) SAME chemical adj polish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:45
-	0	anneal\$3 adj area SAME electropolish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:46
-	4637	anneal\$3 SAME polish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:48
-	1924	(anneal\$3 SAME polish\$3) and electro\$10	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:48
-	16	anneal\$3 SAME electropolish\$3 SAME chemical	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:52
-	1956	anneal\$3 AND 204/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 15:53
-	38	anneal\$3 AND 204/\$.ccls. AND electropolish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:20
-	55192	(anneal\$3 AND 204/\$.ccls. AND electropolish\$3) AND copper NEAR plat\$3 or electroplat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:13
-	25	(anneal\$3 AND 204/\$.ccls. AND electropolish\$3) AND copper	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:13
-	786	anneal\$3 AND chemical NEAR polish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:24
-	0	anneal\$3 AND electrochemical NEAR polish\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:23
-	55203	(anneal\$3 AND chemical NEAR polish\$3) and copper adj plat\$3 or electroplat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/11 16:28
-	23	(anneal\$3 AND chemical NEAR polish\$3) and copper adj plat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/14 10:13

-	9	(anneal\$3 AND electrolytic NEAR polish\$3) and copper adj plat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/14 10:04
-	4	(anneal\$3 AND chemical NEAR polish\$3) and copper adj plat\$3 AND ((anneal\$3 AND electrolytic NEAR polish\$3) and copper adj plat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/14 10:05
-	20	(anneal\$3 AND electrolytic NEAR10 polish\$3) and copper adj plat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/14 10:47
-	11	((anneal\$3 AND chemical NEAR10 polish\$3) and copper adj plat\$3) AND ((anneal\$3 AND electrolytic NEAR10 polish\$3) and copper adj plat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/14 10:48
-	185	(anneal\$3 AND chemical NEAR10 polish\$3) and copper adj plat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/14 11:21